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(12) **United States Design Patent** (10) **Patent No.:** **US D798,832 S**
Hayashida et al. (45) **Date of Patent:** **** Oct. 3, 2017**

(54) **POWER SEMICONDUCTOR DEVICE**

2224/08054; H01L 23/58; H05B 41/14;
H02B 6/4201; G02B 6/4256; G02B
6/4257; G02B 6/4261; G02B 6/4262;
G02B 6/428; G02B 6/4281; H05K 1/18;
H05K 1/181; H05K 1/182; H05K 1/026

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See application file for complete search history.

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(Continued)

(**) Term: **15 Years**

Primary Examiner — Elizabeth J Oswecki

(21) Appl. No.: **29/558,572**

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(57) **CLAIM**

(30) **Foreign Application Priority Data**

The ornamental design for a power semiconductor device, as shown and described.

Sep. 30, 2015 (JP) 2015-021416

DESCRIPTION

(51) **LOC (10) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

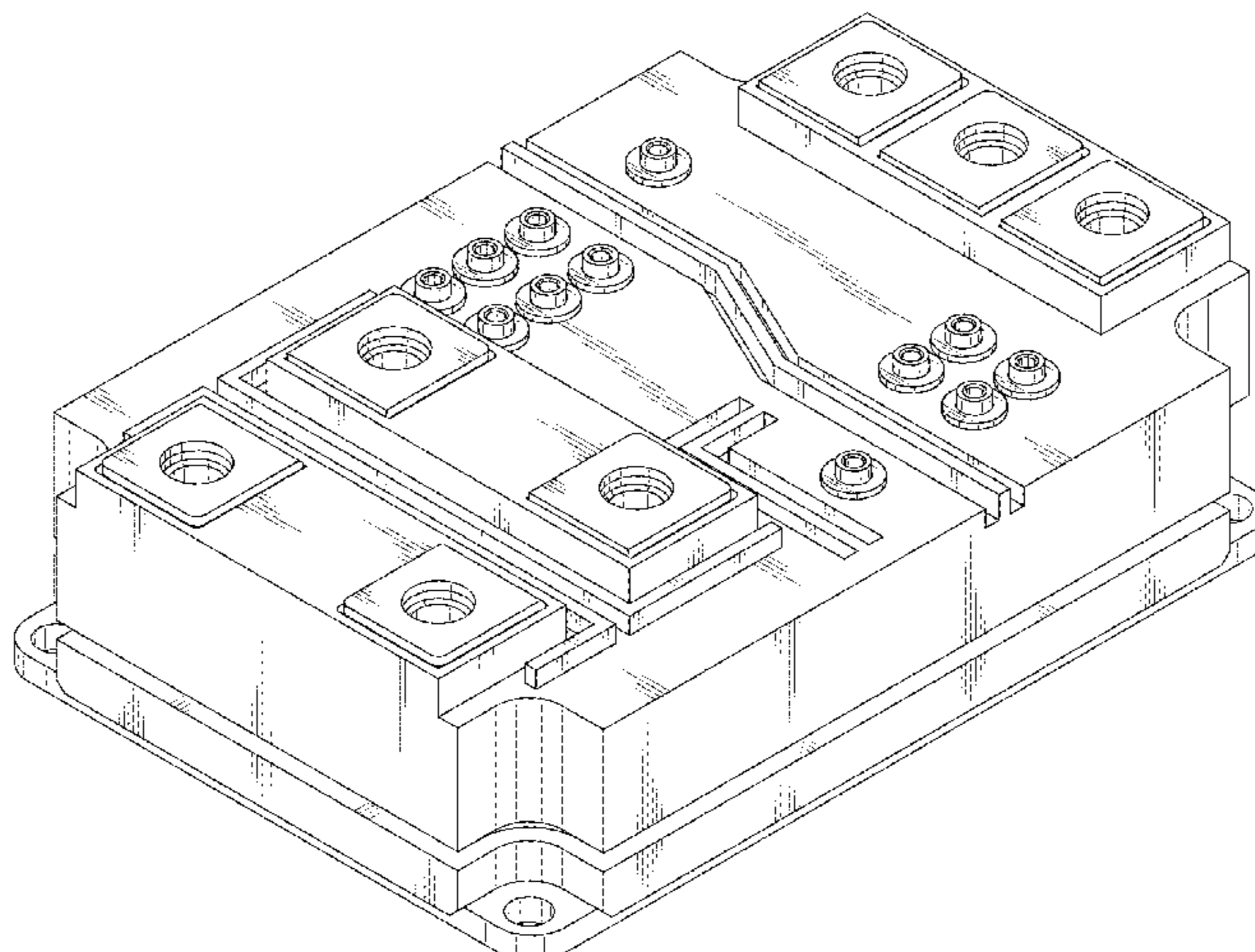
(58) **Field of Classification Search**
USPC D13/182; 257/678, 684, 690, 691;
361/679.01, 713, 728, 736, 760, 761, 772,
361/775, 783, 820; 174/250, 253;
438/15, 25, 26, 51, 55, 63, 64

CPC . H01L 21/00; H01L 2224/42; H01L 2224/43;
H01L 2021/00; H01L 2021/02; H01L
2021/04; H01L 21/4814; H01L 21/4846;
H01L 21/4871; H01L 21/67144; H01L
23/02; H01L 23/13; H01L 23/14; H01L
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2924/1711; H01L 2924/1715; H01L
2924/17151; H01L 2924/181; H01L
2924/1811; H01L 2924/1815; H01L
2924/19042; H01L 2924/1905; H01L

FIG. 1 is a front, left side, bottom perspective view of a power semiconductor device, showing our new design; FIG. 2 is a front, right side, top perspective view thereof; FIG. 3 is a front view thereof; FIG. 4 is a rear view thereof; FIG. 5 is a left side view hereof; FIG. 6 is a right side view thereof; FIG. 7 is a top view thereof; FIG. 8 is a bottom view thereof; FIG. 9 is a cross sectional view taken along line 9-9 in FIG. 3; and, FIG. 10 is another cross sectional view taken along line 10-10 in FIG. 3.

The broken lines in FIG. 4 illustrate unclaimed portions of the power semiconductor device and form no part of the claimed design.

1 Claim, 9 Drawing Sheets



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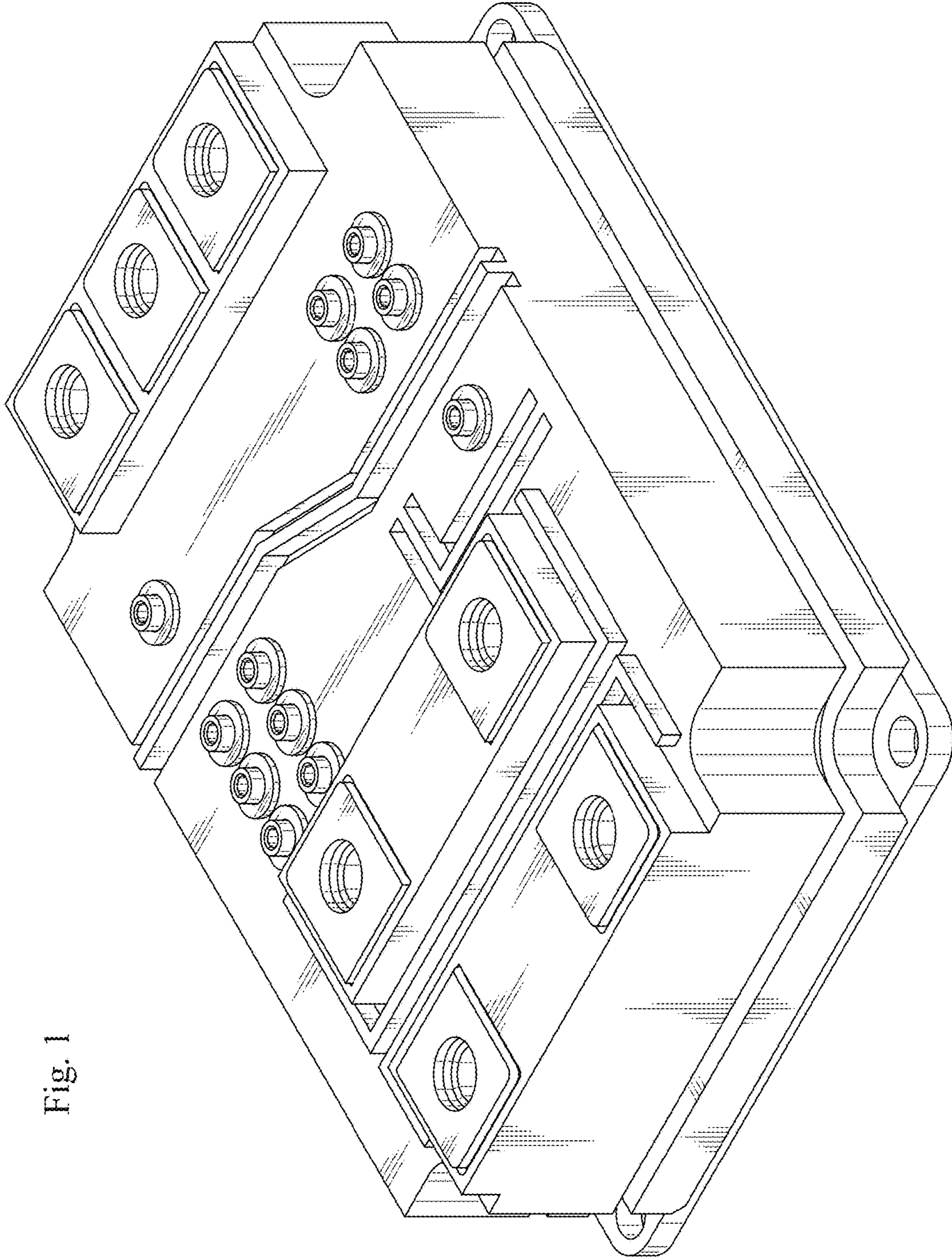


Fig. 1

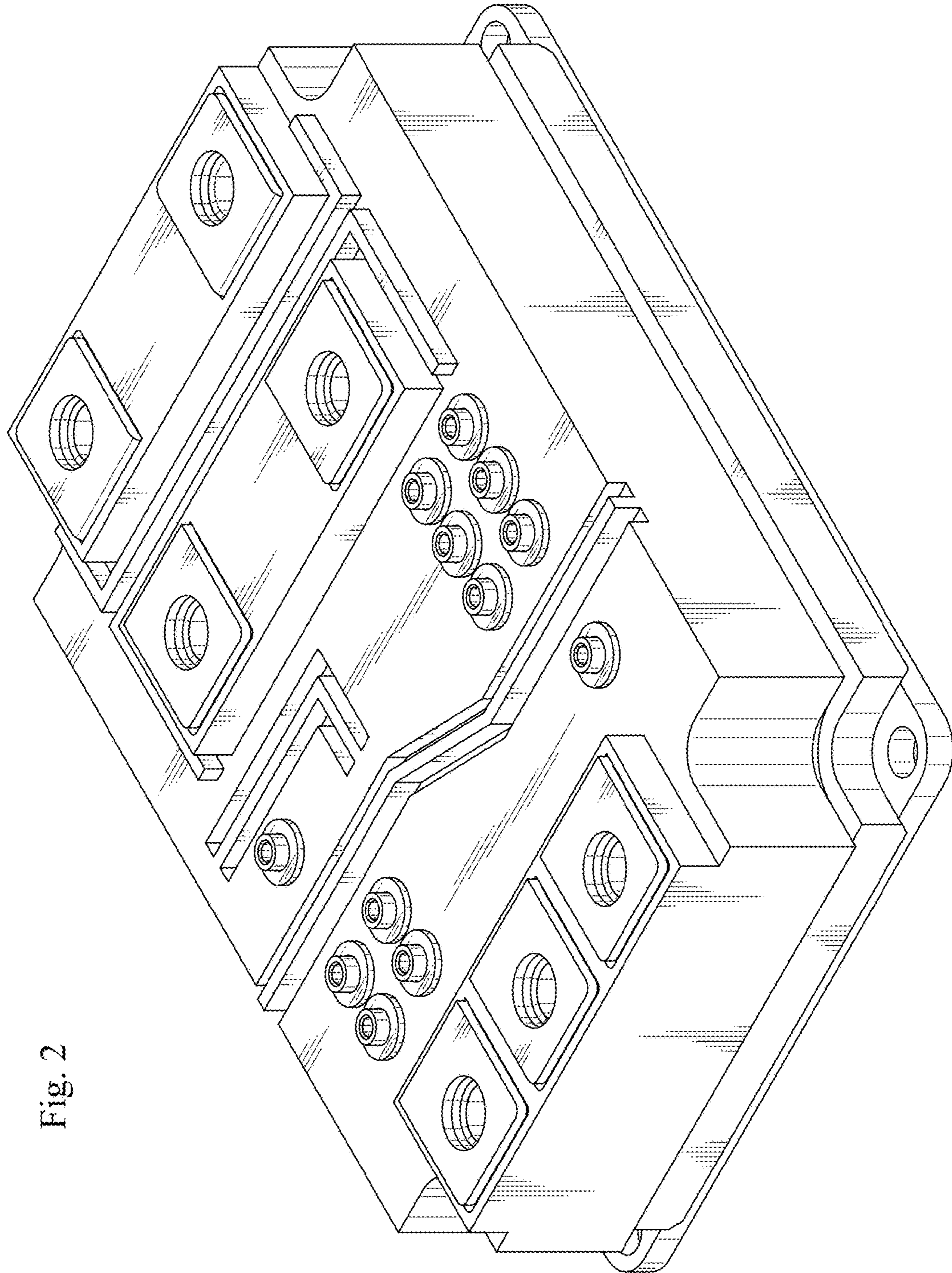


Fig. 2

Fig. 3

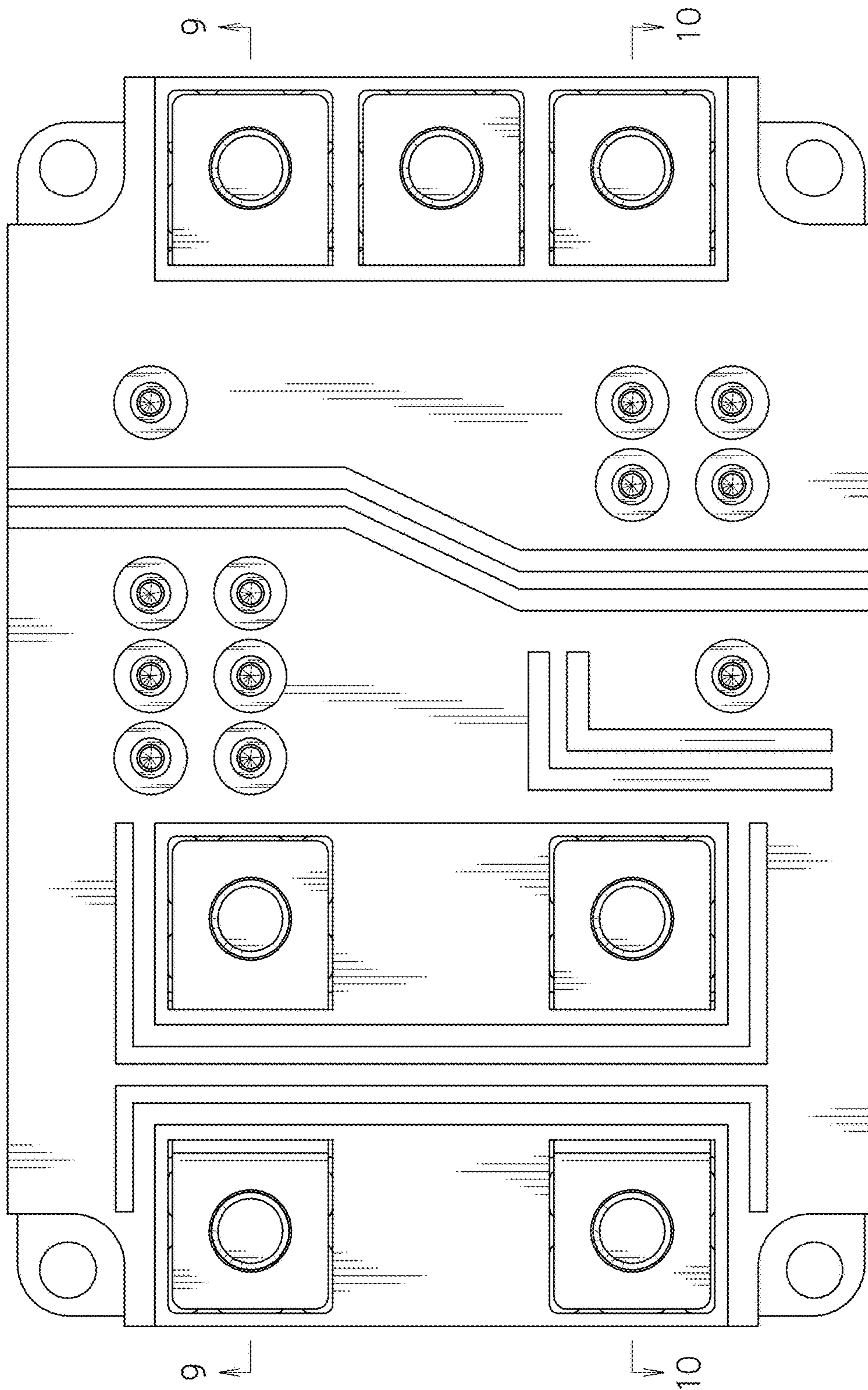


Fig. 4

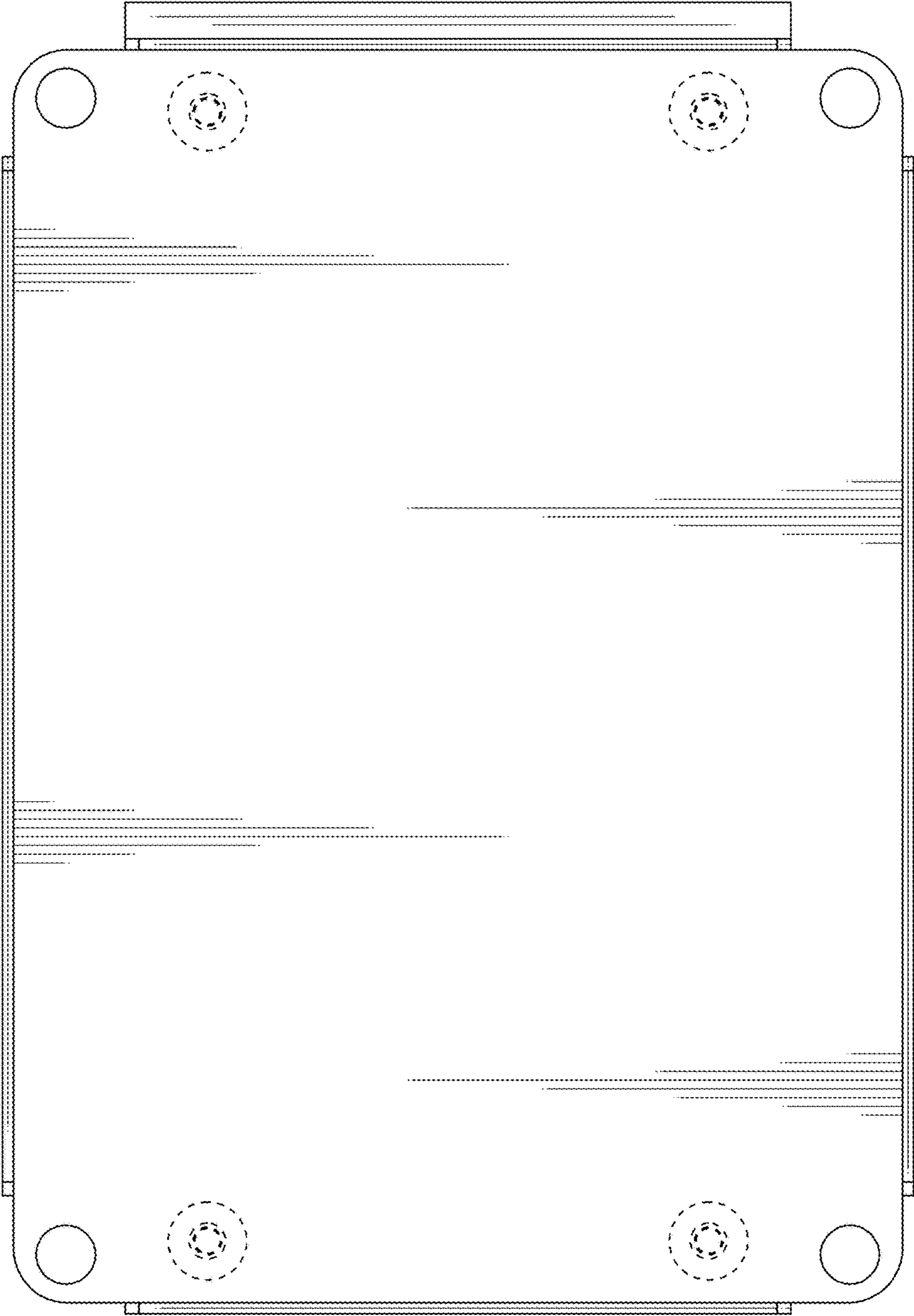


Fig. 6

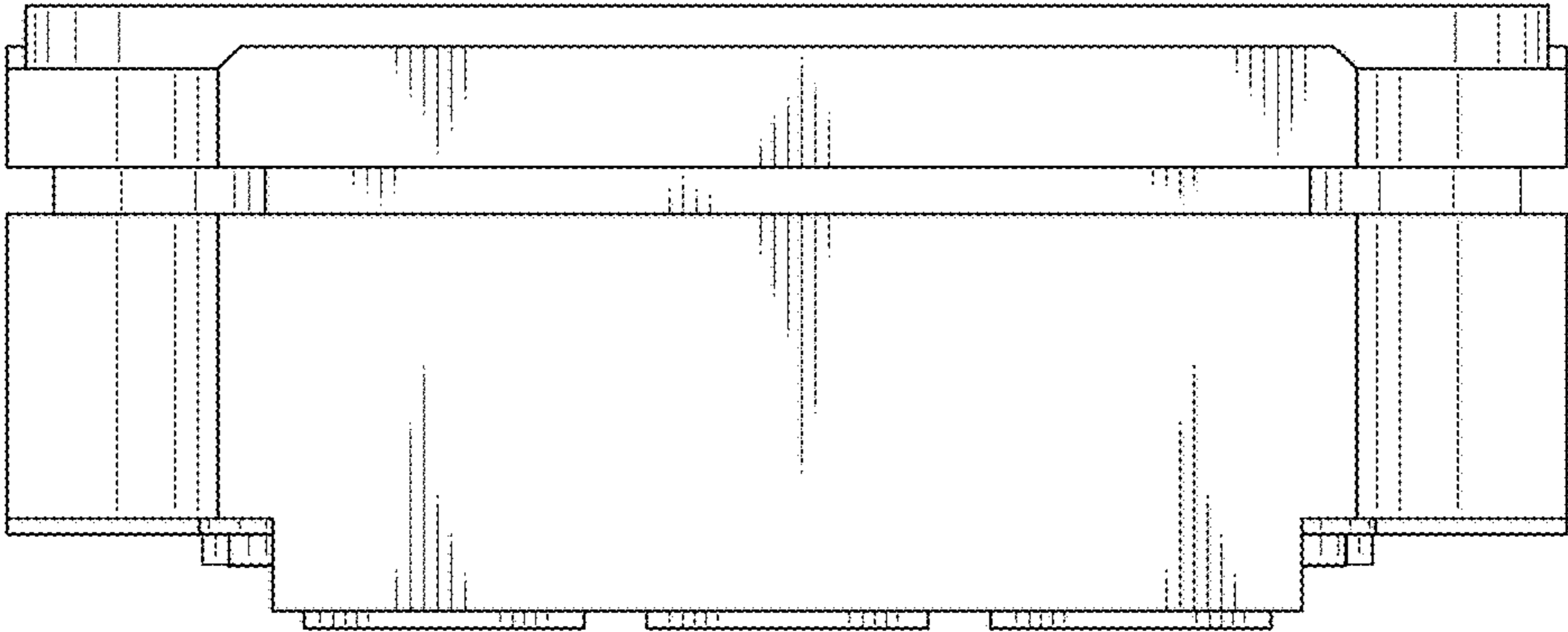


Fig. 5

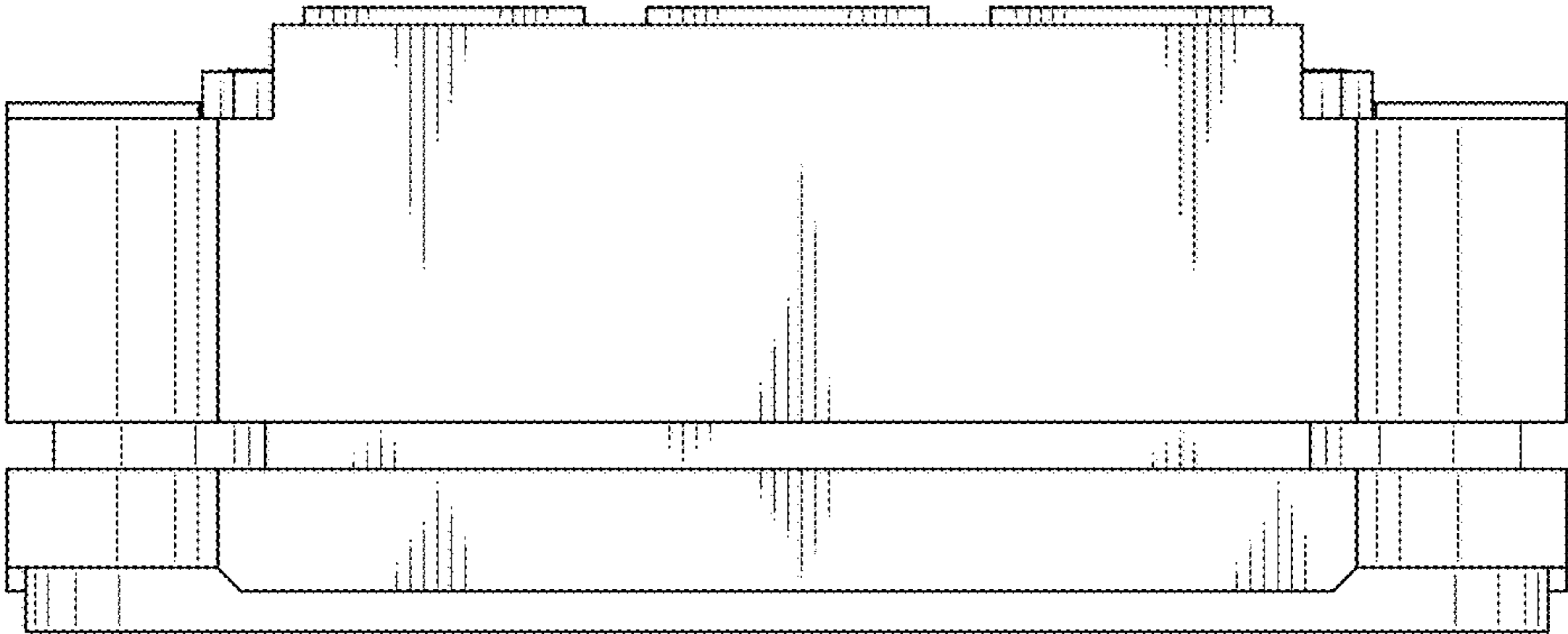


Fig. 7

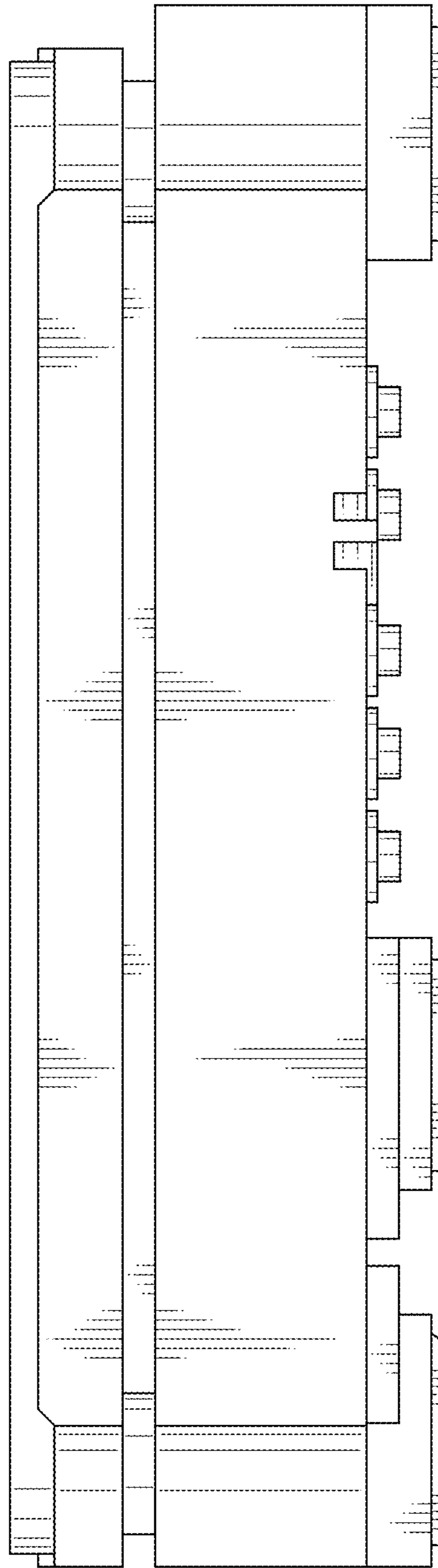
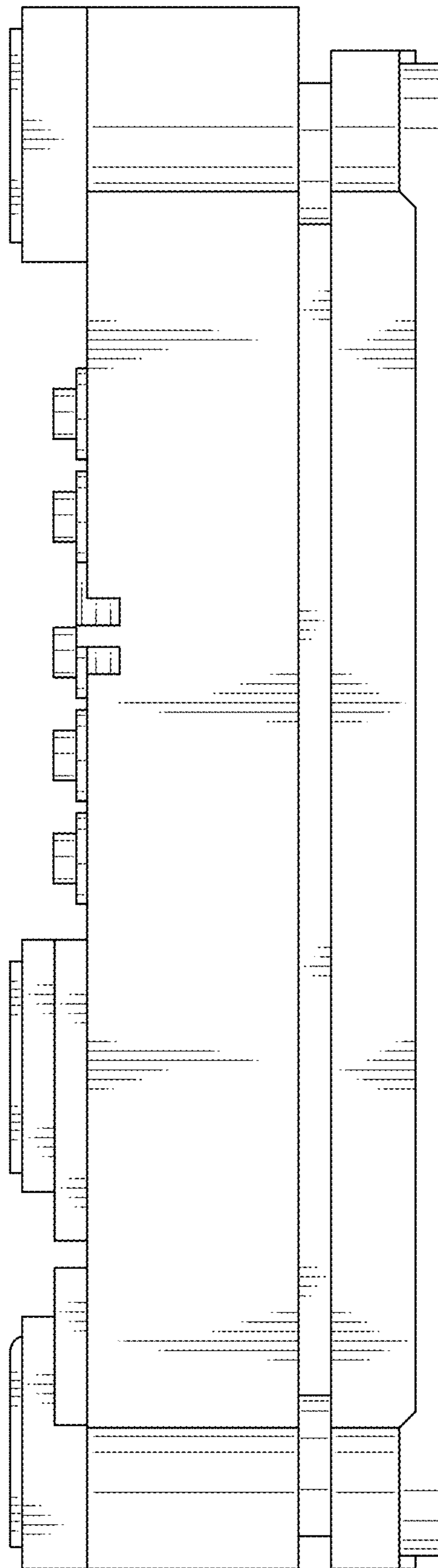


Fig. 8



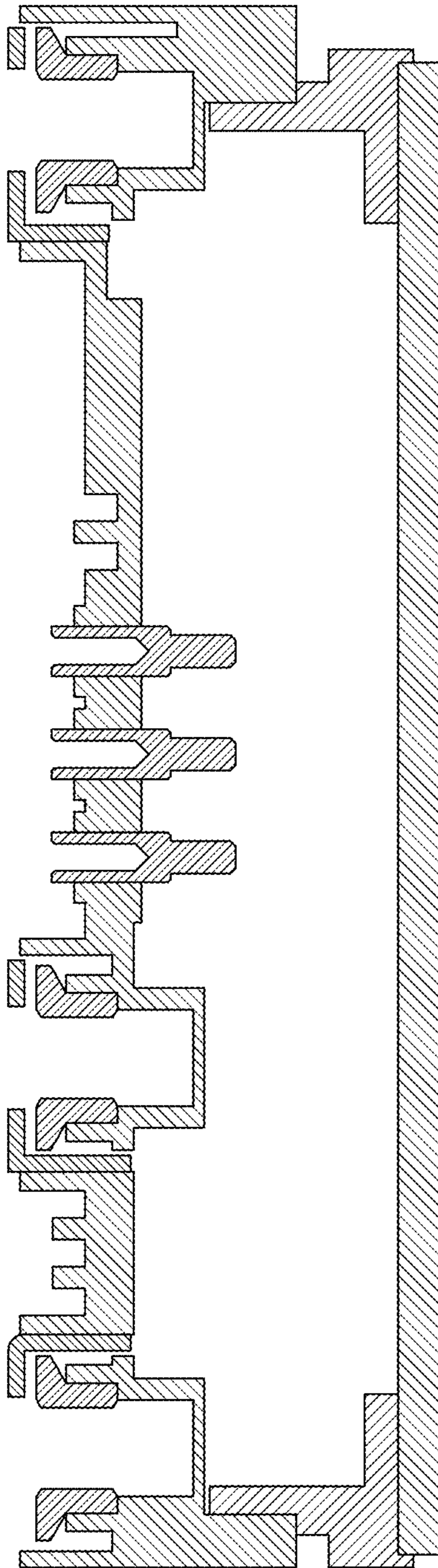


Fig. 9

Fig. 10

